

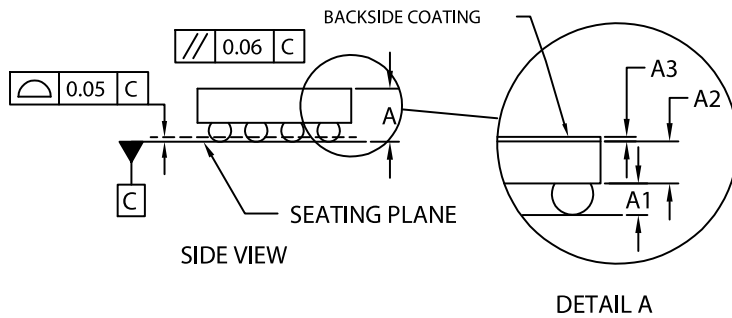
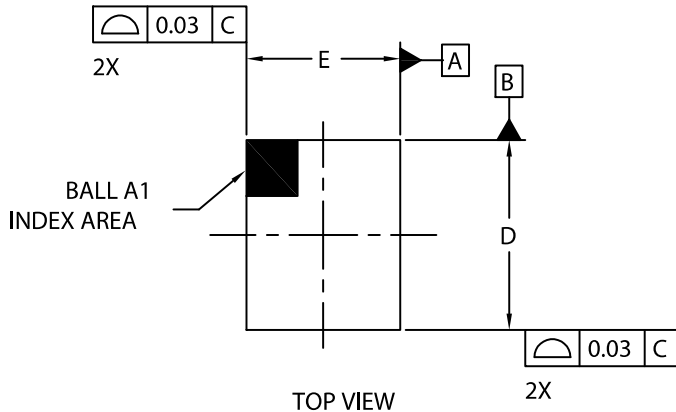


WLCSP20 2.03x1.77x0.585
CASE 567ZF
ISSUE A

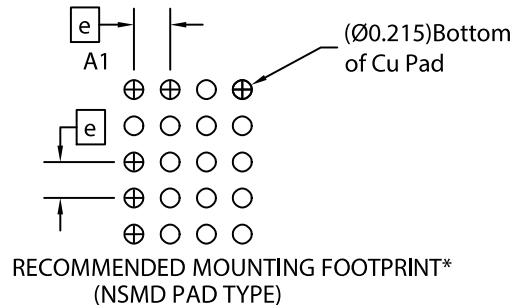
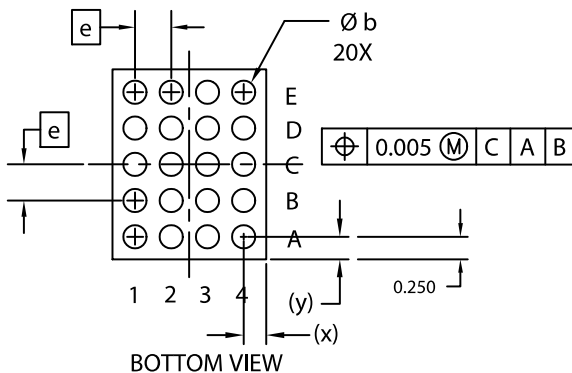
DATE 01 DEC 2020

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

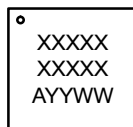


DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.560	0.585	0.610
A1	0.184	0.194	0.204
A2	0.354	0.366	0.378
A3	0.022	0.025	0.028
b	0.240	0.260	0.280
D	2.000	2.030	2.060
E	1.740	1.770	1.800
e	0.40 BSC		
x	0.270	0.285	0.300
y	0.200	0.215	0.230



* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "µ", may or may not be present. Some products may not follow the Generic Marking.

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